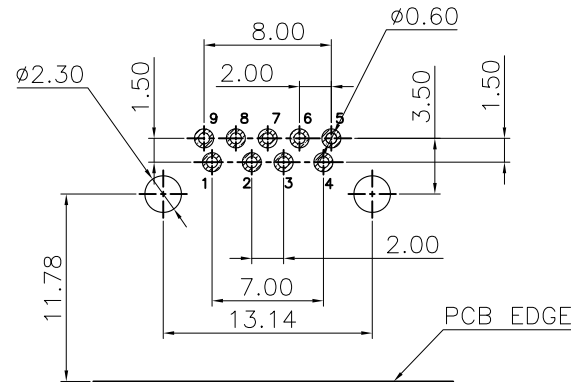
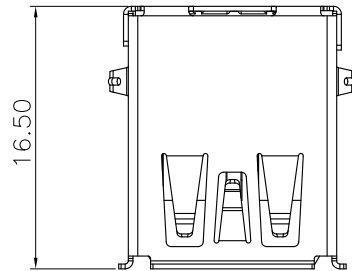


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2014/04/03	Jamie Zie



NOTES:

1.MATERIAL:

1.1 HOUSING: HIGH TEMPERATURE THERAL PLASTIC, UL94-V0; BLUE COLOR .

1.2 CONTACT: COPPER ALLOY .

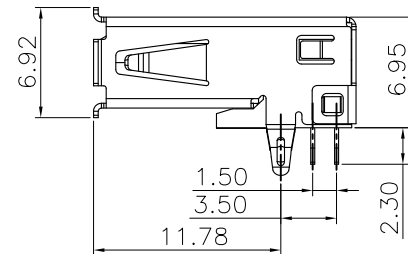
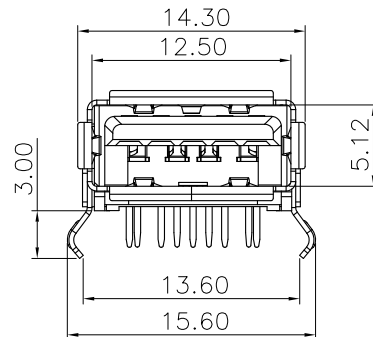
1.3 SHELL: SUS

2.FINISH:

2.1 CONTACT: GOLD FLASH PLATED ON CONTACT AREA, 100μ" MIN. MATTE-TIN ON SOLDER TAIL WITH ENTIRE ONTACT UNDERPLATED 50μ" MIN. NICKEL.

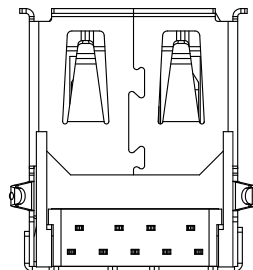
2.2 SHELL: 150μ" MIN. NICKEL OVER 20μ" MIN.

TOLERANCE: ± 0.05 , THICKNESS: 1.6mm
RECOMMENDED PCB LAYOUT
(TOP VIEW)



MATRIX PART NO:

MUSB - 09 - 01 - 52
MATRIX USB — Pin Number — Series number
Planting
01:Gold Flash
15:15u"
30:30u"



PIN No.	SIGNAL NAME	PIN No.	SIGNAL NAME
1	VBUS	6	STDA_SSRX+
2	D-	7	GND_DRAIN
3	D+	8	STDA_SSTX-
4	GND	9	STDA_SSTX+
5	STDA_SSRX-	SHELL	SHIELD

NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ± 0.38 X:XX ± 0.25 X:XXX ± 0.13 ANGLE: $\pm 3^\circ$		DESIGN BY : Jamie Zie	DATE : 2014/04/03	PART NAME: USB 3.0 A TYPE FEMALE R/A DIP H=6.95mm
CHECKED BY: Joyce Cho		DATE : 2014/04/03	PART NO.	MUSB09-01-52
APPROVED BY1: Richard Hsieh		DATE : 2014/04/03	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2014/04/03	DRAW NO.	
SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 1